Title (en)

DEVICE FOR PROCESSING OF SUBSTRATES

Title (de)

VORRICHTUNG ZUM BEHANDELN VON SUBSTRATEN

Title (fr)

DISPOSITIF POUR PROCESSER DES MATERIAUX EN BANDE

Publication

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Application

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Abstract (en)

[origin: WO2017089420A2] The invention relates to a device and a method for processing substrates using a separation system. The problem addressed by the invention is that of providing a device and a method for processing substrates, which permit the separation of processed substrates into one or more waste parts and at least one useful part. In particular, the object of the invention is that of providing a device and a method, which have improved flexibility, for processing substrates. The problem is solved in that: the separation system (2) comprises a transport cylinder (3) and a stripping cylinder (4) associated therewith; the transport cylinder (3) has first openings (12) and a detachably secured pick-up element (5) comprising depressions in which holes are formed, at least one hole covering at least one first opening (12); and the stripping cylinder (4) has a detachably secured pick-up element (5) with protruding regions that correspond to the depressions.

IPC 8 full level

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